

## AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph beginning on line 7 of page 1 with the following rewritten paragraph.

Integrated circuit packages use a variety of means to indicate the orientation of the package. Integrated circuits encapsulated in plastic often have an indentation on the surface of the package to indicate the location of pin one of the package. Other packages used a painted dot, or a chamfered corner to indicate indication the proper orientation. While the indentation in a plastic package is essentially cost free, each of the other means of marking the orientation of the package results in added package cost. The alternate methods also have other shortcomings. For example, marking the package lid does not provide a reference during the fabrication of the package. Likewise, a chamfer on a package corner may be difficult to see under certain conditions. While these shortcomings are of no importance for many integrated circuits, the assembly of which is completely automated, improper keying during hand assembly operations leads to expensive waste in the manufacture of some integrated circuits, most notably microelectromechanical systems (MEMS). Furthermore, some electro-optic MEMS devices typically use a glass plate for the package lid. Markings on the glass lid can cause unwanted reflections that degrade the performance of the device. Additionally, markings on the glass are not available to use to orient the package during assembly.